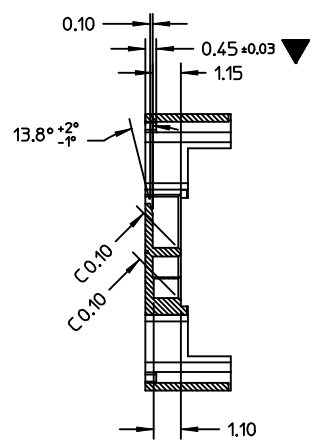
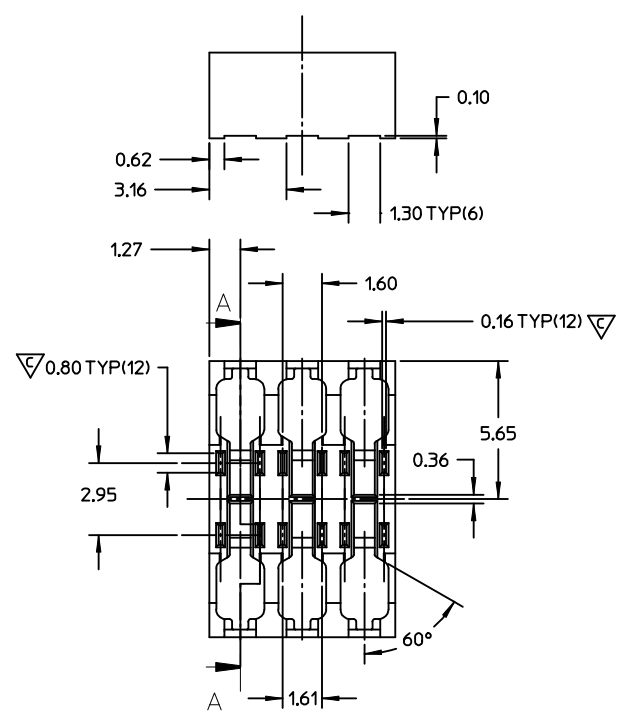
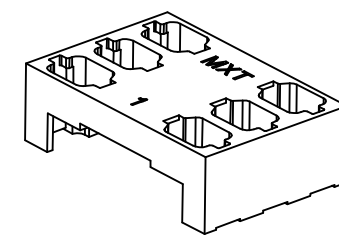
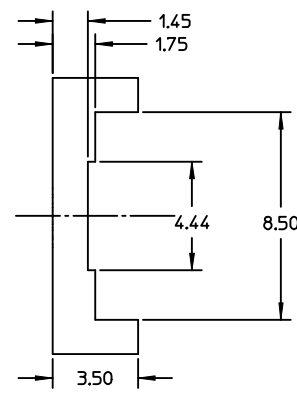
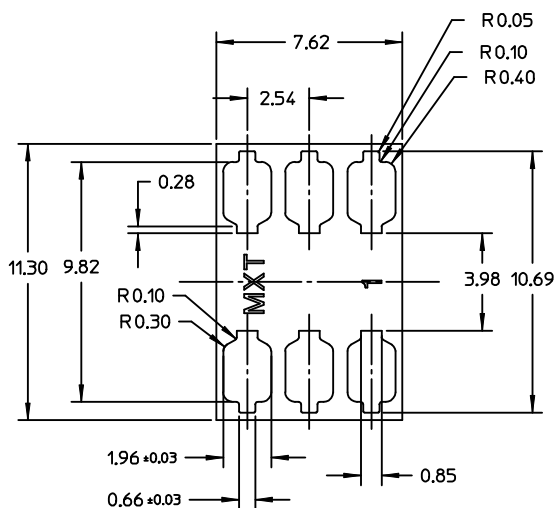


- NOTES:
1. MATERIAL:LCP,30% GLASS FILLED,UL94V-0,COLOR:BLACK PER89992-0393
 2. ALL FLASHES NOT TO EXCEED 0.08MM
 3. BOW IN ALL DIRECTIONS NOT TO EXCEED 0.02MM
 4. ALL UN-DIMENSIONED CORNER MUST BE R0.05MM MAX.
 5. PARTING LINE MISMATCH NOT TO EXCEED 0.05MM MAX.
 6. CAVITY I.D. & LOGO TO BE INTAGLIOED IN A 0.10MM DEEP RECESS

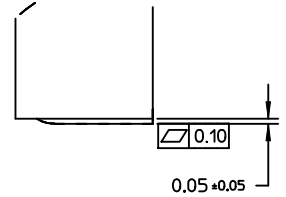
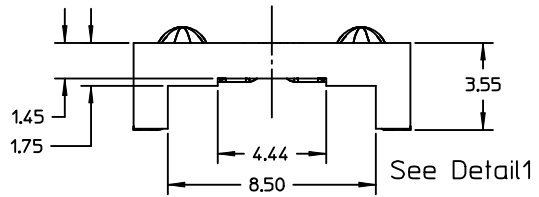
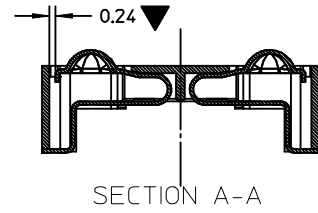
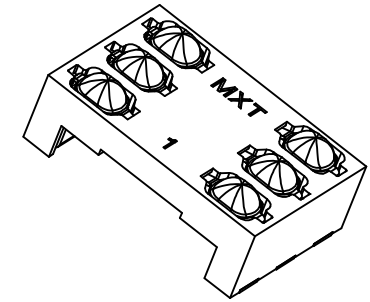
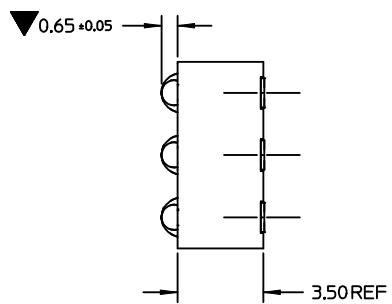
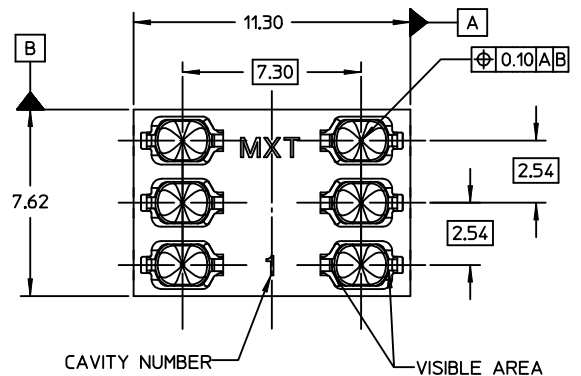
EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR:SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
	DESCRIPTION ▼ = 0 ▽ = 0		mm	INCH	DIMENSION STYLE		TITLE HOUSING OF 3.50MM HIGH SIMCARD CONNECTOR
		4 PLACES	± ---	± ---	MM ONLY		
		3 PLACES	± ---	± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED MATERIAL NO. ENTER-PART E-67687-602 DOCUMENT NO. E-67687-602 SHEET NO. 1 OF 1
2 PLACES	± 0.05	± ---	CHECKED BY LZHAO	DATE 2003/01/30			
1 PLACE	± 0.10	± ---	APPROVED BY SAMHUANG	DATE 2003/01/30			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



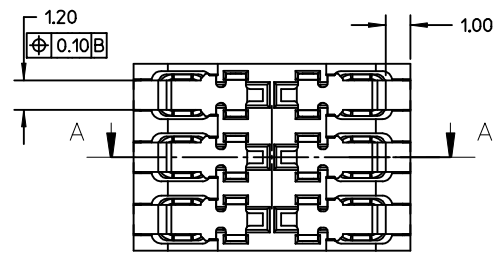
- NOTES:
1. MATERIAL:LCP,30% GLASS FILLED,UL94V-0,COLOR:BLACK PER89992-0393
 2. ALL FLASHES NOT TO EXCEED 0.08MM
 3. BOW IN ALL DIRECTIONS NOT TO EXCEED 0.02MM
 4. ALL UN-DIMENSIONED CORNER MUST BE R0.05MM MAX.
 5. PARTING LINE MISMATCH NOT TO EXCEED 0.05MM MAX.
 6. CAVITY I.D. & LOGO TO BE INTAGLIOED IN A 0.10MM DEEP RECESS

EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR:SHUANG 2003/03/27	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DIMENSION STYLE MM ONLY		TITLE HOUSING OF 3.50MM HIGH SIMCARD CONNECTOR		
		2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED		
		ANGULAR ± 1 °		CHECKED BY LZHAO	DATE 2003/01/30	MATERIAL NO. ENTER-PART	DOCUMENT NO. E-67687-602	SHEET NO. 1 OF 1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SAMHUANG 2003/01/30		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-602	676873502
TERMINAL	E-67687-604	676873504



Detail1

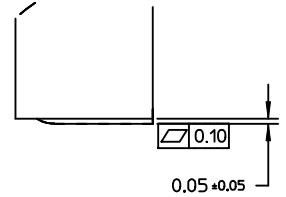
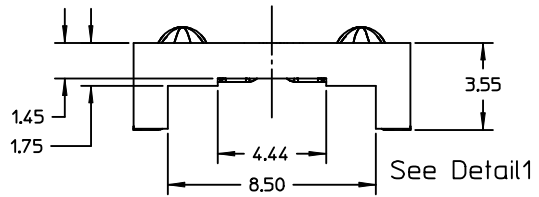
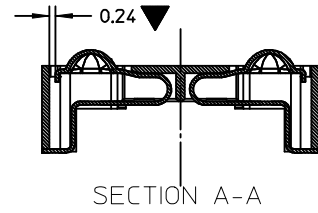
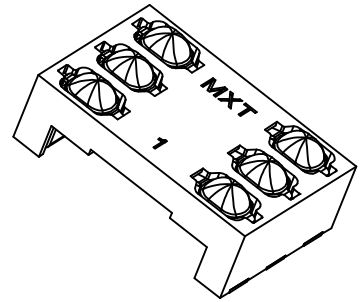
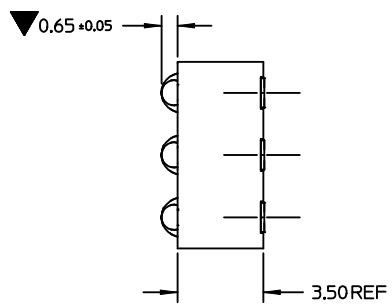
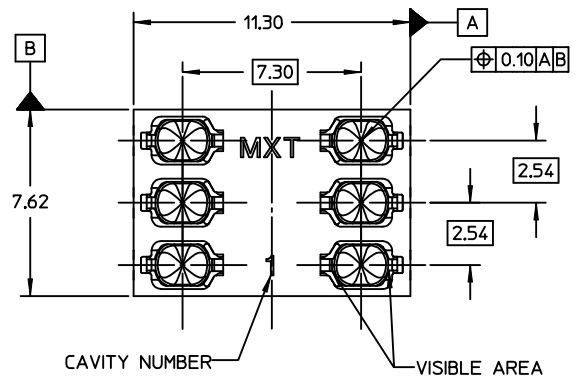


NOTES:

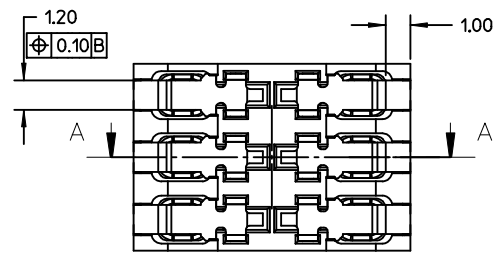
- 1 MATERIAL:
HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK
TERMINAL: PHOSPHOR BRONZE C5210, FULL HARD, THICKNESS : 0.15MM
- 2. PLATING:
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
- 3. PACKAGING: TAPE REEL
- 4. PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN: SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION ▽ - 0 ◻ - 0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE ASSEMBLY OF SIM CARD CONNECTOR	
		4 PLACES ± ---	± ---	DRAWN BY SSUN	DATE 2003/01/30		
		3 PLACES ± ---	± ---	CHECKED BY LZHAO	DATE 2003/01/30		
A	2 PLACES ± 0.05	± ---	APPROVED BY SAMHUANG	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. E-67687-603	
	1 PLACE ± 0.10	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 1		
	ANGULAR ± 2 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-602	676873502
TERMINAL	E-67687-604	676873504



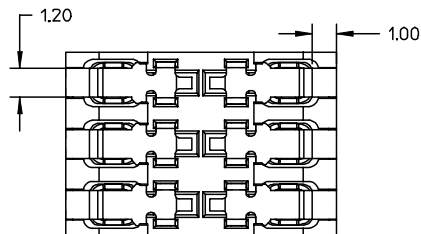
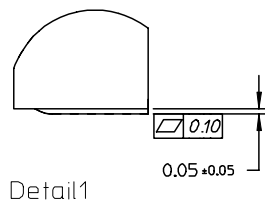
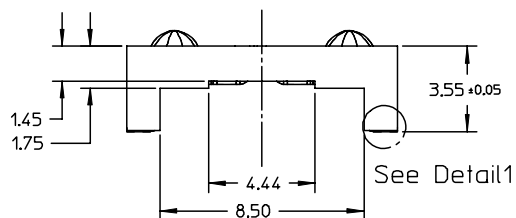
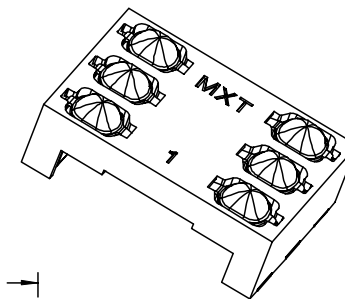
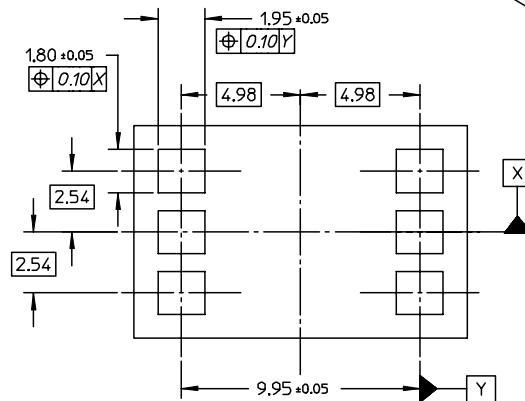
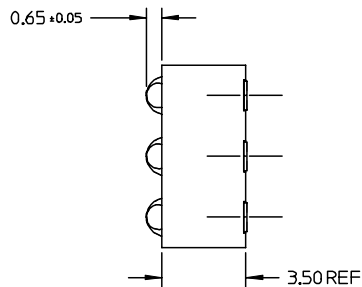
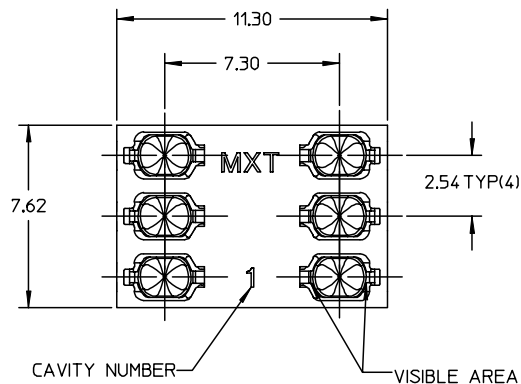
Detail1



NOTES:

- 1 MATERIAL:
HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK
TERMINAL: PHOSPHOR BRONZE C5210, FULL HARD, THICKNESS : 0.15MM
- 2. PLATING:
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
- 3. PACKAGING: TAPE REEL
- 4. PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN: SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION ▽ - 0 C - 0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE ASSEMBLY OF SIM CARD CONNECTOR	
		4 PLACES ± ---	± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED MATERIAL NO. 676873501 DOCUMENT NO. E-67687-603 SHEET NO. 1 OF 1	
		3 PLACES ± ---	± ---	CHECKED BY LZHAO	DATE 2003/01/30		
2 PLACES ± 0.05	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
1 PLACE ± 0.10	± ---	ANGULAR ± 2 °					



NOTES:

1 MATERIAL:

HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK
 TERMINAL:COPPER ALLOY

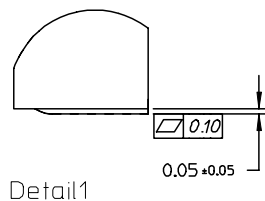
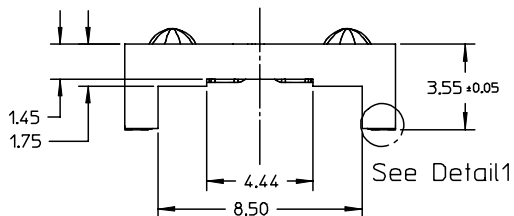
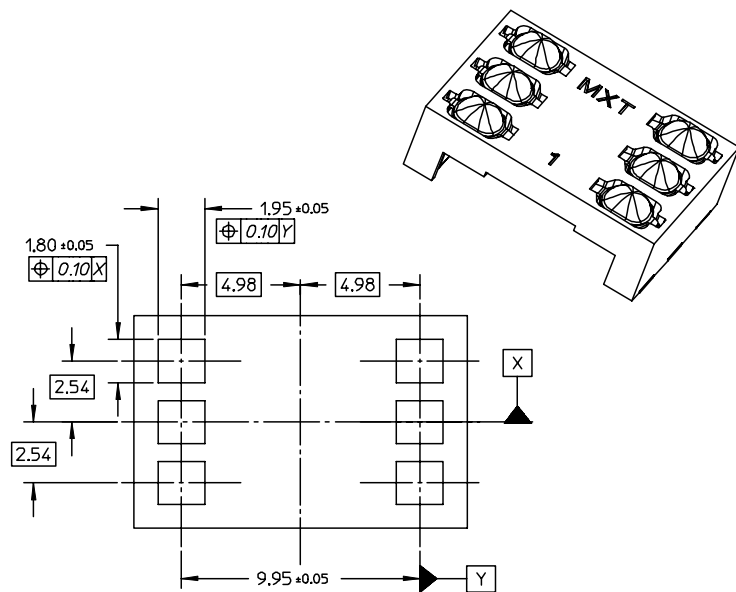
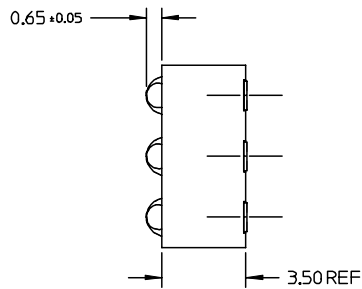
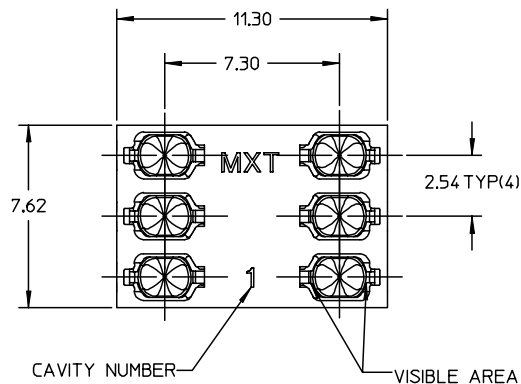
2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-002

EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION ▼ = 0 ▽ = 0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY DATE SSUN 2003/01/30				
		2 PLACES ± 0.2 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY DATE LZHAO 2003/01/30				
REV A	ANGULAR ± 3 °	DRAFT WHERE APPLICABLE		APPROVED BY DATE SAMHUANG 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. SD-67687-601	SHEET NO. 1 OF 1	
MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



NOTES:

1 MATERIAL:

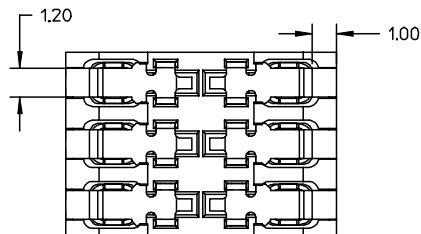
HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK
 TERMINAL:COPPER ALLOY

2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-002



EC NO: SH2003-0029 DRWN:SSUN 2003/03/27 CHKD: 2003/03/27 APPR: SHUANG 2003/03/27	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
		mm	INCH	DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY SSUN	DATE 2003/01/30	MOLEX INCORPORATED		
		2 PLACES ± 0.2 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY LZHAO	DATE 2003/01/30	MATERIAL NO. 676873501	DOCUMENT NO. SD-67687-601	SHEET NO. 1 OF 1
REV A	DESCRIPTION	ANGULAR ± 3 °		DRAFT WHERE APPLICABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		